

09-26-2002

HEET

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To the Honorable Commissioner of

102234407

the attached original documents or copy thereof.

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Takaki SAITOU

9-20-02

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: August 19, 2002

2. Name and address of receiving party(ies):

Name: Hitachi, Ltd.

Address: 6, Kanda Surugadai 4-chome

Chiyoda-ku

City: Tokyo

State/Prov.:

Country: Japan

ZIP:

Additional name(s) & address(es)

☒ Yes ☐ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: August 19, 2002

Patent Application No.

Filing date

B. Patent No.(s)

09/23/2002 HLE333 00000007 10247505

04 FC:581

40.00 05

Additional numbers

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mitchell W. Shapiro

Registration No. 31,568

Address: Miles & Stockbrige P.C.

1751 Pinnacle Drive

Suite 500

City: McLean

State/Prov.: VA

Country: United States

ZIP: 22102

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mitchell W. Shapiro

Name of Person Signing

Signature

September 20, 2002

Date

3

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Name (line 2)

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Name (line 1)

Name (line 2)

Receiving Party(ies)

☐ Mark if additional names of receiving parties attached

Enter additional Receiving Party(ies)

Name (line 1)

Hitachi Hokkai Semiconductor, Ltd.

Name (line 2)

Address (line 1)

145, Azanakajima, Nanaecho,

Address (line 2)

Kameda-gun

Address (line 3)

Hokkaido

City

Japan

State/Country

Zip Code

Name (line 1)

Name (line 2)

Address (line 1)

Address (line 2)

Address (line 3)

City

State/Country

Zip Code

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Patent Application Number(s)

Patent Number(s)

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 145, Azanakajima, Nanaecho, Kameda-gun, Hokkaido, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Hitachi Hokkai Semiconductor, Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Takaki Saitou (Takaki SAITOU)

19 / August / 2002

2) _____

3) _____

4) _____

5) _____

6) _____

7) _____

8) _____

9) _____

10) _____
